

NVMFS5826NL

Power MOSFET

60 V, 24 mΩ, 26 A, Single N-Channel

Features

- Small Footprint (5x6 mm) for Compact Design
- Low $R_{DS(on)}$ to Minimize Conduction Losses
- Low Q_G and Capacitance to Minimize Driver Losses
- NVMFS5826NLWF – Wettable Flanks Product
- AEC-Q101 Qualified and PPAP Capable
- These are Pb-Free Devices and RoHS Compliant

MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V_{DSS}	60	V
Gate-to-Source Voltage			V_{GS}	± 20	V
Continuous Drain Current $R_{\Psi J-mb}$ (Notes 1, 2, 3, 4)	Steady State	$T_{mb} = 25^{\circ}\text{C}$	I_D	26	A
		$T_{mb} = 100^{\circ}\text{C}$		19	
Power Dissipation $R_{\Psi J-mb}$ (Notes 1, 2, 3)		$T_{mb} = 25^{\circ}\text{C}$	P_D	39	W
		$T_{mb} = 100^{\circ}\text{C}$		19	
Continuous Drain Current $R_{\theta JA}$ (Notes 1, 3, 4)	Steady State	$T_A = 25^{\circ}\text{C}$	I_D	8.0	A
		$T_A = 100^{\circ}\text{C}$		6.0	
Power Dissipation $R_{\theta JA}$ (Notes 1 & 3)		$T_A = 25^{\circ}\text{C}$	P_D	3.6	W
		$T_A = 100^{\circ}\text{C}$		1.8	
Pulsed Drain Current	$T_A = 25^{\circ}\text{C}$, $t_p = 10\text{ }\mu\text{s}$		I_{DM}	130	A
Operating Junction and Storage Temperature			T_J , T_{stg}	-55 to +175	$^{\circ}\text{C}$
Source Current (Body Diode)			I_S	32	A
Single Pulse Drain-to-Source Avalanche Energy ($T_J = 25^{\circ}\text{C}$, $V_{DD} = 24\text{ V}$, $V_{GS} = 10\text{ V}$, $I_{L(pk)} = 20\text{ A}$, $L = 0.1\text{ mH}$, $R_G = 25\text{ }\Omega$)			E_{AS}	20	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			T_L	260	$^{\circ}\text{C}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Mounting Board (top) – Steady State (Notes 2, 3)	$R_{\Psi J-mb}$	3.9	$^\circ\text{C}/\text{W}$
Junction-to-Ambient – Steady State (Note 3)	$R_{\theta JA}$	42	

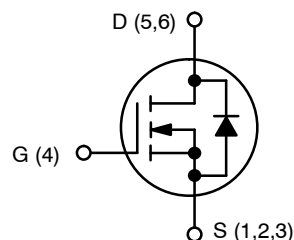
1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
2. Psi (Ψ) is used as required per JESD51-12 for packages in which substantially less than 100% of the heat flows to single case surface.
3. Surface-mounted on FR4 board using a 650 mm², 2 oz. Cu pad.
4. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.



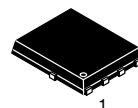
ON Semiconductor®

<http://onsemi.com>

$V_{(BR)DSS}$	$R_{DS(ON)} \text{ MAX}$	$I_D \text{ MAX}$
60 V	24 mΩ @ 10 V	26 A
	32 mΩ @ 4.5 V	

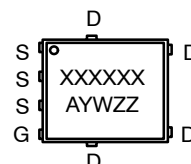


N-CHANNEL MOSFET



DFN5
(SO-8FL)
CASE 488AA
STYLE 1

MARKING DIAGRAM



- A = Assembly Location
Y = Year
W = Work Week
ZZ = Lot Traceability

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

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ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 250 μA	60			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V, V _{DS} = 60 V	T _J = 25°C		1.0	μA
			T _J = 125°C		10	
Gate-to-Source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V			±100	nA

ON CHARACTERISTICS (Note 5)

Gate Threshold Voltage	V _{GS(TH)}	V _{GS} = V _{DS} , I _D = 250 μA	1.5		2.5	V
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V, I _D = 10 A		18	24	mΩ
		V _{GS} = 4.5 V, I _D = 10 A		24	32	
Forward Transconductance	g _{FS}	V _{DS} = 15 V, I _D = 5 A		8.0		S

CHARGES AND CAPACITANCES

Input Capacitance	C _{iss}	V _{GS} = 0 V, f = 1 MHz, V _{DS} = 25 V		850		pF
Output Capacitance	C _{oss}			85		
Reverse Transfer Capacitance	C _{rss}			50		
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 4.5 V, V _{DS} = 48 V, I _D = 10 A		9.1		nC
Threshold Gate Charge	Q _{G(TH)}			1.0		
Gate-to-Source Charge	Q _{GS}			3.0		
Gate-to-Drain Charge	Q _{GD}			4.0		
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 10 V, V _{DS} = 48 V, I _D = 10 A		17		nC

SWITCHING CHARACTERISTICS (Note 6)

Turn-On Delay Time	t _{d(ON)}	V _{GS} = 4.5 V, V _{DS} = 48 V, I _D = 10 A, R _G = 2.5 Ω		9.0		ns
Rise Time	t _r			32		
Turn-Off Delay Time	t _{d(OFF)}			15		
Fall Time	t _f			24		

DRAIN-SOURCE DIODE CHARACTERISTICS

Forward Diode Voltage	V _{SD}	V _{GS} = 0 V, I _S = 10 A	T _J = 25°C		0.8	1.2	V
			T _J = 125°C		0.7		
Reverse Recovery Time	t _{RR}	V _{GS} = 0 V, dI _S /dt = 100 A/μs, I _S = 10 A		15		ns	
Charge Time	t _a			11			
Discharge Time	t _b			4.0			
Reverse Recovery Charge	Q _{RR}			11		nC	

5. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.

6. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS

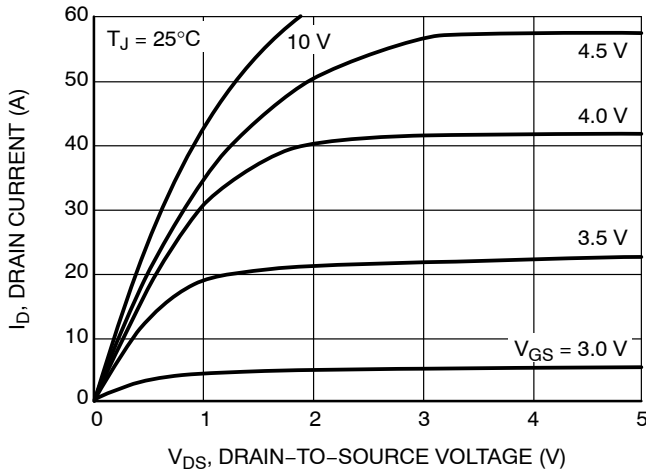


Figure 1. On-Region Characteristics

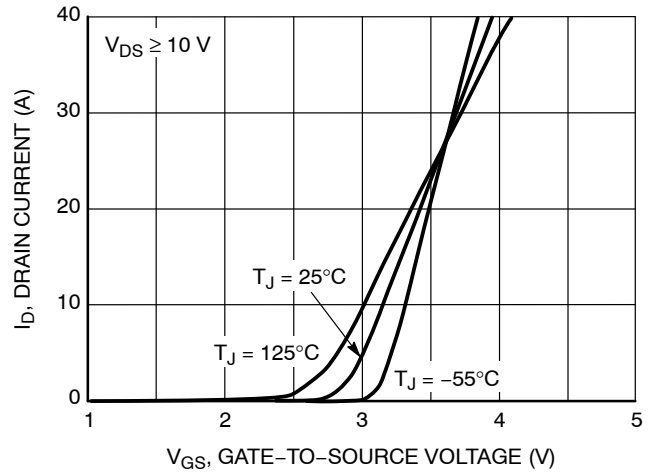


Figure 2. Transfer Characteristics

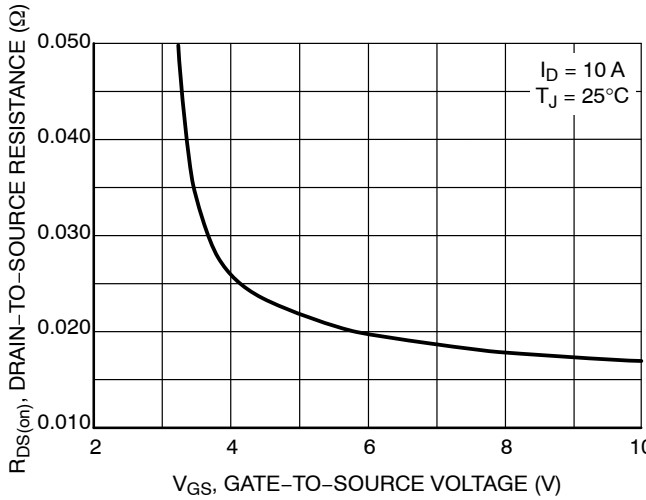


Figure 3. On-Resistance vs. Gate-to-Source Voltage

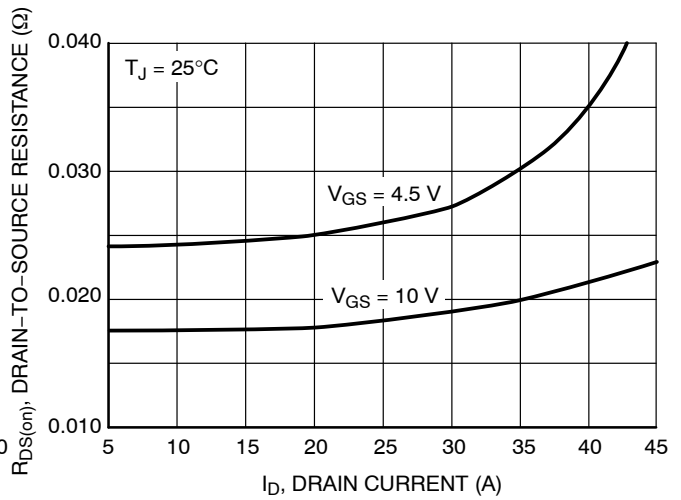


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

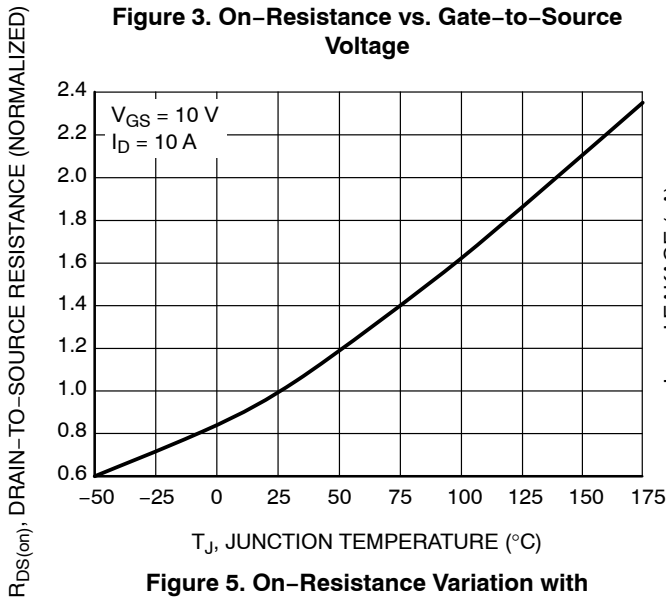


Figure 5. On-Resistance Variation with Temperature

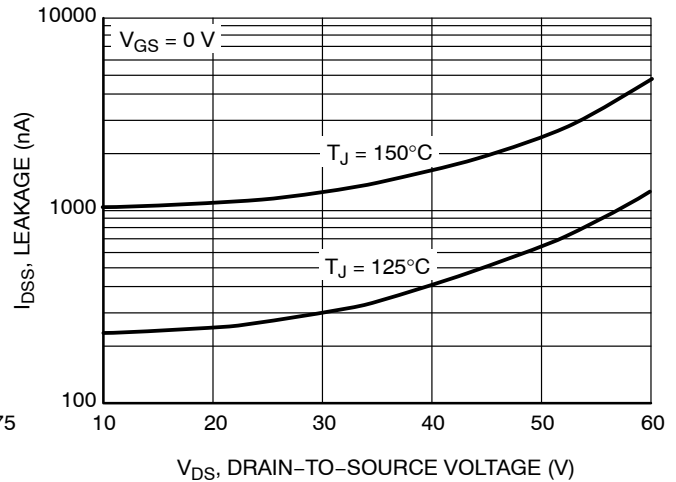


Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL CHARACTERISTICS

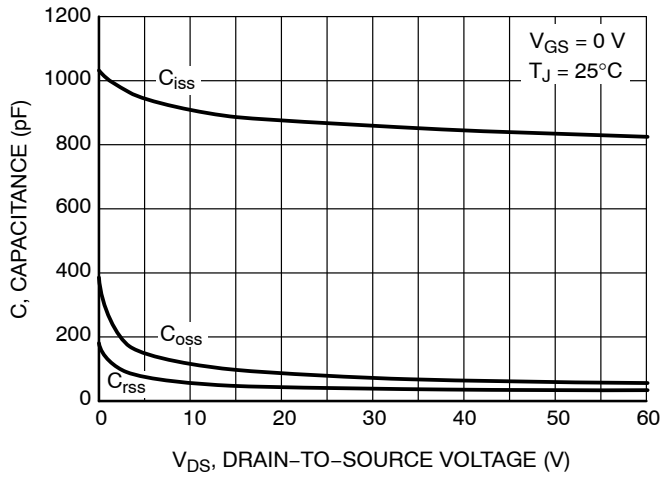


Figure 7. Capacitance Variation

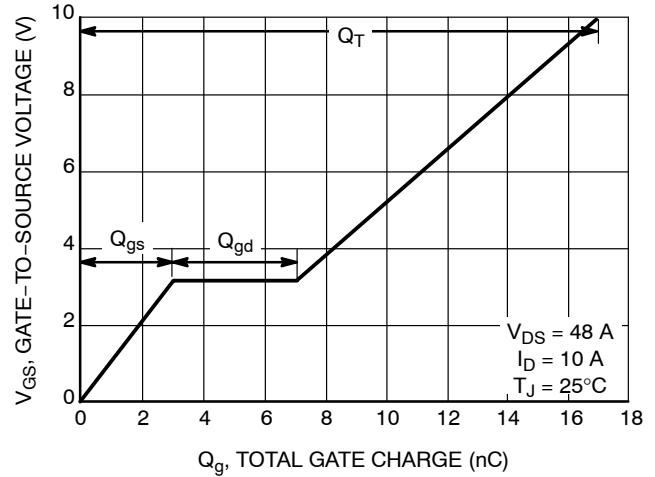


Figure 8. Gate-to-Source Voltage vs. Total Charge

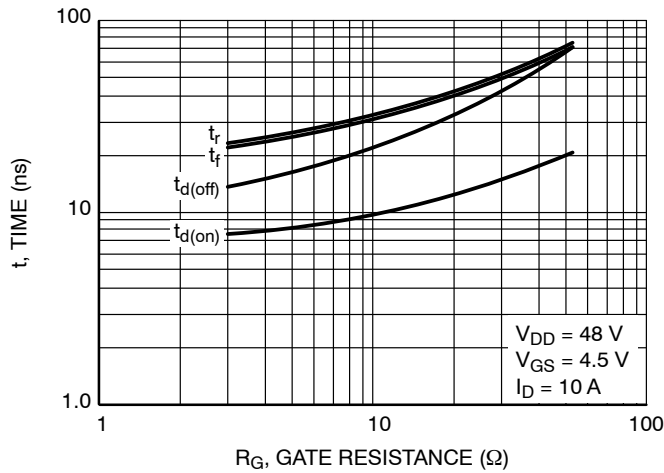


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

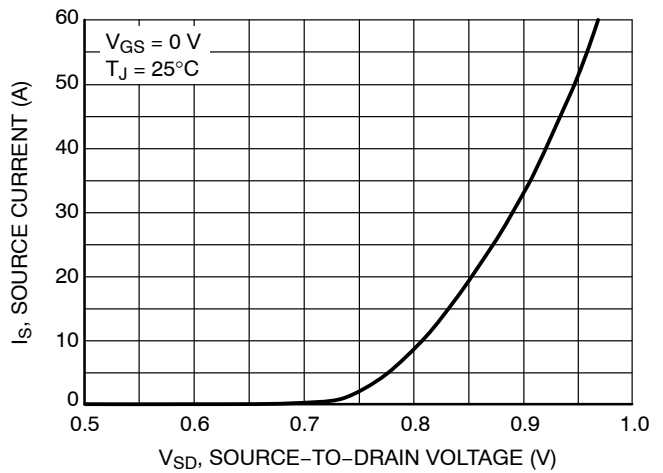


Figure 10. Diode Forward Voltage vs. Current

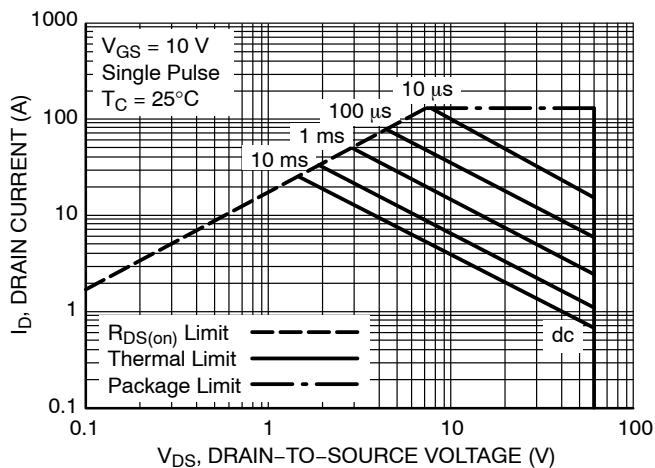


Figure 11. Maximum Rated Forward Biased Safe Operating Area

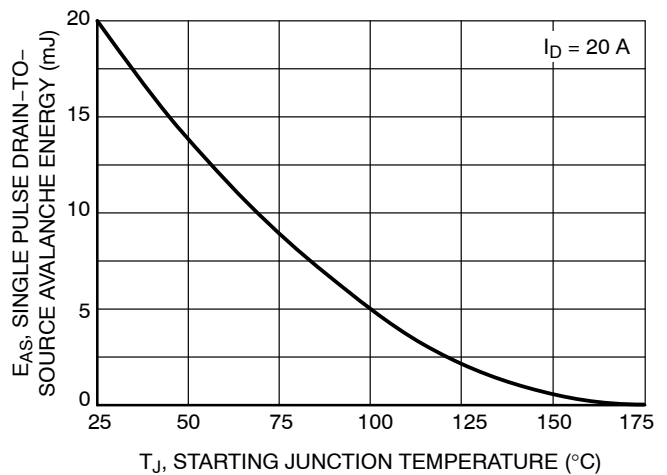


Figure 12. Maximum Avalanche Energy vs. Starting Junction Temperature

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TYPICAL CHARACTERISTICS

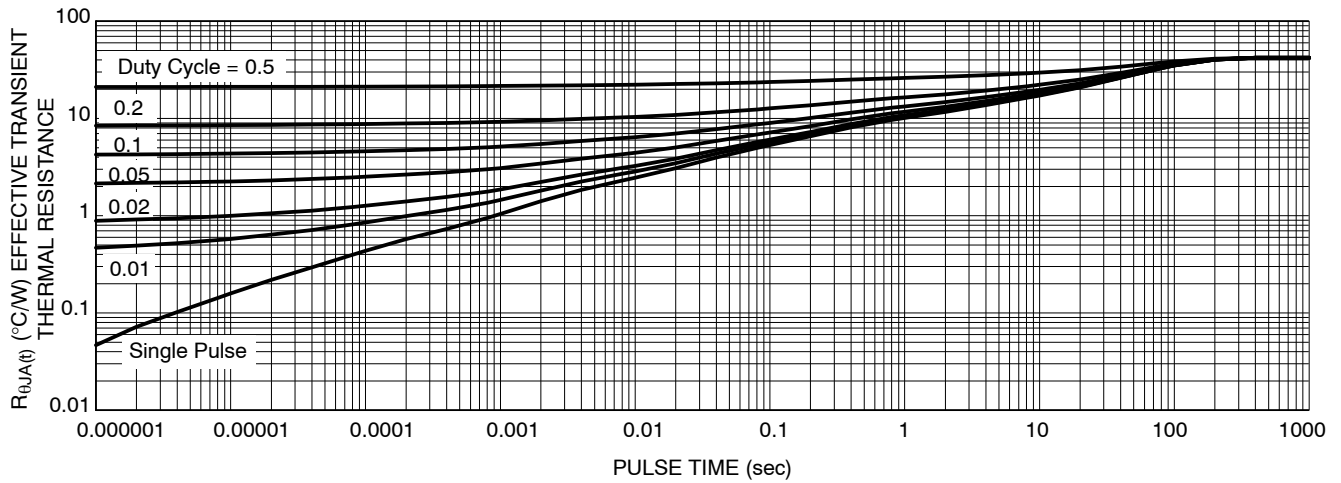


Figure 13. Thermal Response

DEVICE ORDERING INFORMATION

Device	Marking	Package	Shipping†
NVMFS5826NLT1G	V5826L	DFN5 (Pb-Free)	1500 / Tape & Reel
NVMFS5826NLWFT1G	5826LW	DFN5 (Pb-Free)	1500 / Tape & Reel
NVMFS5826NLT3G	V5826L	DFN5 (Pb-Free)	5000 / Tape & Reel
NVMFS5826NLWFT3G	5826LW	DFN5 (Pb-Free)	5000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

The drawing illustrates the mechanical specifications for a 5-pin D-subminiature connector. It includes the following views and dimensions:

- TOP VIEW:** Shows the overall footprint with dimensions D (total width), D1 (width to center), E1 (height to contact), and E (total height). It also indicates the pin positions (1, 2, 3, 4) and a 2X feature.
- SIDE VIEW:** Shows the profile of the connector with dimensions A (height to contact), A1 (height to seating plane), and C (seating plane). It also indicates a 2X feature.
- DETAIL A:** A circular detail view of the contact area, showing dimensions c (radius), 4X (diameter), 3X (width), and e (height).
- SOLDERING FOOTPRINT*:** A detailed view of the soldering footprint, showing dimensions 3X (1.270), 4X (0.750), 4X (1.000), 0.965, 1.330, 2X (0.495), 3.200, 0.475, 4.530, 2X (1.530), and 4.560.
- BOTTOM VIEW:** Shows the underside of the connector with dimensions a (width), b (width), L (height), K (height), M (height), L1 (height), D2 (width), and G (width). It also indicates the PIN 5 (EXPOSED PAD) and a 2X feature.

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE BURRS.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.90	1.00	1.10
A1	0.00	---	0.05
b	0.33	0.41	0.51
c	0.23	0.28	0.33
D	5.15 BSC		
D1	4.70	4.90	5.10
D2	3.80	4.00	4.20
E	6.15 BSC		
E1	5.70	5.90	6.10
E2	3.45	3.65	3.85
e	1.27 BSC		
G	0.51	0.61	0.71
K	1.20	1.35	1.50
L	0.51	0.61	0.71
L1	0.05	0.17	0.20
M	3.00	3.40	3.80
Ø	0°	---	12°

PIN 1. SOURCE
2. SOURCE
3. SOURCE
4. GATE
5. DRAIN

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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